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14-May-2025

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
OPA2835ID	Active	Production	SOIC (D) 8	75 BULK	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835ID.Z	Active	Production	SOIC (D) 8	75 BULK	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IDGS	Active	Production	VSSOP (DGS) 10	80 BULK	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IDGS.Z	Active	Production	VSSOP (DGS) 10	80 BULK	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IDGSR	Active	Production	VSSOP (DGS) 10	2500 LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IDGSR.Z	Active	Production	VSSOP (DGS) 10	2500 LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IDR.Z	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IRMCR	Active	Production	UQFN (RMC) 10	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IRMCR.Z	Active	Production	UQFN (RMC) 10	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IRMCT	Active	Production	UQFN (RMC) 10	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IRMCT.Z	Active	Production	UQFN (RMC) 10	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IRUNR	Active	Production	QFN (RUN) 10	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IRUNR.Z	Active	Production	QFN (RUN) 10	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IRUNRG4.Z	Active	Production	QFN (RUN) 10	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IRUNT	Active	Production	QFN (RUN) 10	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA2835IRUNT.Z	Active	Production	QFN (RUN) 10	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2835
OPA835IDBVR	Active	Production	SOT-23 (DBV) 6	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	QUM
OPA835IDBVR.Z	Active	Production	SOT-23 (DBV) 6	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	QUM
OPA835IDBVT	Active	Production	SOT-23 (DBV) 6	250 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	QUM
OPA835IDBVT.Z	Active	Production	SOT-23 (DBV) 6	250 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	QUM
OPA835IRUNR	Active	Production	QFN (RUN) 10	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	835
OPA835IRUNR.Z	Active	Production	QFN (RUN) 10	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	835
OPA835IRUNT	Active	Production	QFN (RUN) 10	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	835
OPA835IRUNT.Z	Active	Production	QFN (RUN) 10	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	835

⁽¹⁾ Status: For more details on status, see our product life cycle.



PACKAGE OPTION ADDENDUM

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- (2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- (3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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